Product/Process Change Notice - PCN 18_0064 Rev. B

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Bump Site Transfer and Qualification of Select 6L and 8L SOT23 Flip Chip on Lead Packages

Publication Date: 26-Oct-2018

Effectivity Date: 28-Jan-2019 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Adding Qualification Results Summary for commercial grade.

Description Of Change:

1) Bumping Site change from Amkor Taiwan (AT5) to Chipbond, Taiwan (CB4)
2) Die Level Bumping change from High Lead Bumping to Cu Pillar / SnAg Bumping
3) Assembly change from High Lead bumped die Flip Chip on Lead to Cu Pillar / SnAg bumped die Flip Chip on Lead.

See detailed change description attachment in the supporting documents section of this PCN.

Reason For Change:

High lead bumping manufacturer, Amkor (AT5) will no longer provide the aforementioned High Lead wafer bumping process. Bumping process will transfer to Chipbond (CB4) using Cu Pillar / SnAg bumping which is compliant to environmental regulation (lead-free bump).

Impact of the change (positive or negative) on fit, form, function & reliability:

No change on fit, form, function or reliability.

Product Identification *(this section will describe how to identify the changed material)*

No visible external difference on the assembled part. The difference (change from High Lead bumping to Cu Pillar SnAg bumping) can be observed thru x-ray. Material will be traced by "Date Code" and "Assembly Lot Number".

Summary of Supporting Information:

Qualification will be performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Detailed Change Description

ADI_PCN_18_0064_Rev_B_Change Description.docx

Attachment 2: Type: Qualification Plan

ADI_PCN_18_0064_Rev_B_000311_Qualification Plan Summary for SOT23 Automotive.pdf

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Attachment 3: Type: Qualification Plan

ADI_PCN_18_0064_Rev_B_000313_Qualification Plan Summary for SOT_23 for Commercial.pdf

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Attachment 4: Type: Delta Qualification Matrix

ADI_PCN_18_0064_Rev_B_DeQuMa for ADG819 FCOL.xlsm

Attachment 5: Type: Qualification Results Summary

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.			
Americas: PCN_Americas@analog.com	**Europe:** PCN_Europe@analog.com	**Japan:** PCN_Japan@analog.com	**Rest of Asia:** PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Existing Parts - Product Family / Model Number (54)				
AD5060 / AD5060ARJZ-1500RL7	AD5060 / AD5060ARJZ-2500RL7	AD5060 / AD5060BRJZ-1500RL7	AD5060 / AD5060BRJZ-1REEL7	AD5060 / AD5060BRJZ-2500RL7
AD5060 / AD5060BRJZ-2REEL7	AD5060 / AD5060YRJZ-1500RL7	AD5061 / AD5061BRJZ-1500RL7	AD5061 / AD5061BRJZ-2500RL7	AD5061 / AD5061BRJZ-2REEL7
AD5061 / AD5061YRJZ-1500RL7	AD5061 / AD5061YRJZ-1REEL7	AD5062 / AD5062BRJZ-1500RL7	AD5062 / AD5062BRJZ-1REEL7	AD5062 / AD5062BRJZ-2500RL7
AD5062 / AD5062BRJZ-2REEL7	AD5620 / AD5620BRJZ-1500RL7	AD5620 / AD5620BRJZ-2500RL7	AD5620 / AD5620BRJZ-2REEL7	AD5640 / AD5640BRJZ-1500RL7
AD5640 / AD5640BRJZ-1REEL7	AD5640 / AD5640BRJZ-2500RL7	AD5660 / AD5660ARJZ-1500RL7	AD5660 / AD5660ARJZ-1REEL7	AD5660 / AD5660ARJZ-2500RL7
AD5660 / AD5660ARJZ-2REEL7	AD5660 / AD5660ARJZ-3500RL7	AD5660 / AD5660BRJZ-1500RL7	AD5660 / AD5660BRJZ-1REEL7	AD5660 / AD5660BRJZ-2500RL7
AD5660 / AD5660BRJZ-2REEL7	AD5660 / AD5660BRJZ-3500RL7	AD5662 / AD5662ARJZ-1500RL7	AD5662 / AD5662ARJZ-2REEL7	AD5662 / AD5662BRJZ-1500RL7
AD5662 / AD5662BRJZ-1REEL7	AD5662 / AD5662BRJZ-2500RL7	AD5662 / AD5662BRJZ-2REEL7	AD5680 / AD5680BRJZ-1500RL7	AD5680 / AD5680BRJZ-2500RL7
AD5680 / AD5680BRJZ-2REEL7	AD7680 / AD7680ARJZ-REEL7	AD7680 / AD7680BRJZ-R2	AD7680 / AD7680BRJZ-REEL7	AD7940 / AD7940BRJZ-REEL7
ADG801 / ADG801BRTZ-500RL7	ADG801 / ADG801BRTZ-REEL	ADG801 / ADG801BRTZ-REEL7	ADG802 / ADG802BRTZ-500RL7	ADG802 / ADG802BRTZ-REEL7
ADG819 / AD15/136Z-0REEL7	ADG819 / ADG819BRTZ-500RL7	ADG819 / ADG819BRTZ-REEL	ADG819 / ADG819BRTZ-REEL7	

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	23-May-2018	30-Sep-2018	Initial Release
Rev. A	08-Oct-2018	10-Jan-2019	Addition of P/N AD5640BRJZ-2500RL7.
Rev. B	26-Oct-2018	28-Jan-2019	Adding Qualification Results Summary for commercial grade.

PCN 18_0064

PCN Title: Bump Site Transfer and Qualification of Select 6L and 8L SOT23 Flip Chip on Lead Packages

Change Items	**From**	**To**
Bumping Site	Amkor Taiwan (AT5)	Chipbond, Taiwan (CB4)
Die Level Bumping	High Lead Bumping	Cu Pillar/SnAg Bumping
Assembly	High Lead bumped die Flip Chip on Lead assembly with Solder Screen Printing on leadframe step before Flip Chip attachment on leadframe	Cu Pillar/SnAg bumped die Flip Chip on Lead assembly process where the Solder Screen Printing on leadframe step is replaced with Flux Dip step before Flip Chip attachment on the leadframe